



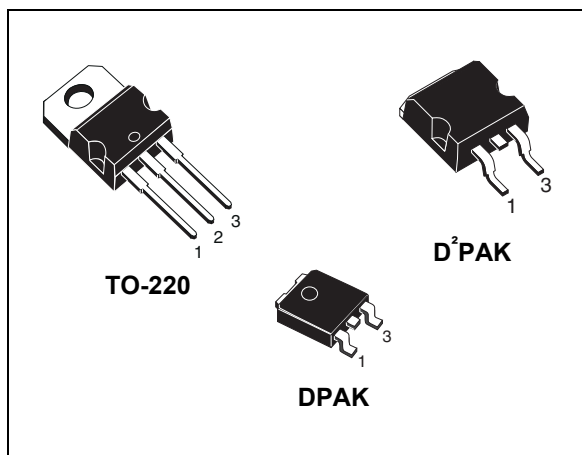
STGB10NC60K - STGD10NC60K STGP10NC60K

N-channel 600V - 10A - D²PAK / TO-220 / DPAK
Short circuit rated PowerMESH™ IGBT

General features

| Type | V _{CE} | V _{CE(sat)} Max @25°C | I _C @100°C |
|-------------|-----------------|-----------------------------------|--------------------------|
| STGB10NC60K | 600V | <2.5V | 10A |
| STGP10NC60K | 600V | <2.5V | 10A |
| STGD10NC60K | 600V | <2.5V | 10A |

- Lower on voltage drop (V_{cesat})
- Lower C_{RES} / C_{IES} ratio (no cross-conduction susceptibility)
- Very soft ultra fast recovery antiparallel diode
- Short circuit withstand time 10μs



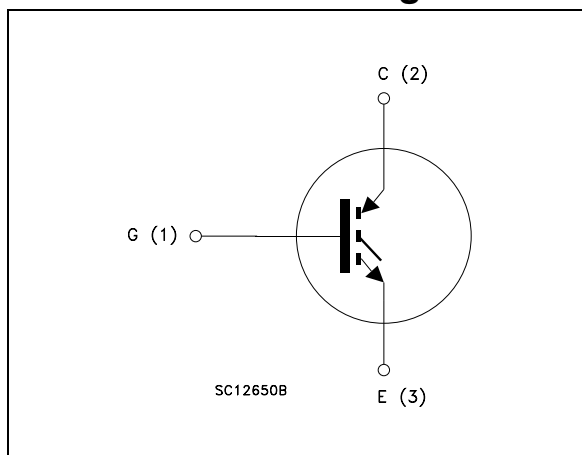
Description

Using the latest high voltage technology based on a patented strip layout, STMicroelectronics has designed an advanced family of IGBTs, the PowerMESH™ IGBTs, with outstanding performances. The suffix “K” identifies a family optimized for high frequency motor control applications with short circuit withstand capability.

Applications

- High frequency motor controls
- SMPS and PFC in both hard switch and resonant topologies
- Motor drivers

Internal schematic diagram



Order codes

| Part number | Marking | Package | Packaging |
|---------------|-----------|--------------------|-------------|
| STGB10NC60KT4 | GB10NC60K | D ² PAK | Tape & reel |
| STGP10NC60K | GP10NC60K | TO-220 | Tube |
| STGD10NC60KT4 | GD10NC60K | DPAK | Tape & reel |

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1 Electrical ratings

Table 1. Absolute maximum ratings

| Symbol | Parameter | Value | Unit |
|----------------|--|-------------|------------------|
| V_{CES} | Collector-emitter voltage ($V_{GS} = 0$) | 600 | V |
| $I_C^{(1)}$ | Collector current (continuous) at $T_C = 25^\circ\text{C}$ | 20 | A |
| $I_C^{(1)}$ | Collector current (continuous) at $T_C = 100^\circ\text{C}$ | 10 | A |
| $I_{CM}^{(2)}$ | Collector current (pulsed) | 30 | A |
| V_{GE} | Gate-emitter voltage | ± 20 | V |
| P_{TOT} | Total dissipation at $T_C = 25^\circ\text{C}$ | 60 | W |
| T_{stg} | Storage temperature | - 55 to 150 | $^\circ\text{C}$ |
| T_j | Operating junction temperature | | |
| T_{scw} | Short circuit withstand time | 10 | μs |
| T_l | Maximum lead temperature for soldering purpose (for 10sec. 1.6 mm from case) | 300 | $^\circ\text{C}$ |

1. Calculated according to the iterative formula:

$$I_C(T_C) = \frac{T_{JMAX} - T_C}{R_{THJ-C} \times V_{CESAT(MAX)}(T_C, I_C)}$$

2. Pulse width limited by max junction temperature

Table 2. Thermal resistance

| Symbol | Parameter | Value | Unit |
|----------------|---|-------|---------------------------|
| $R_{thj-case}$ | Thermal resistance junction-case Max | 2.08 | $^\circ\text{C}/\text{W}$ |
| $R_{thj-amb}$ | Thermal resistance junction-ambient Max | 62.5 | $^\circ\text{C}/\text{W}$ |

2 Electrical characteristics

($T_{CASE}=25^{\circ}C$ unless otherwise specified)

Table 3. Static

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|---------------|---|--|------|------|-----------|---------|
| $V_{BR(CES)}$ | Collector-emitter breakdown voltage | $I_C = 1mA, V_{GE} = 0$ | 600 | | | V |
| $V_{CE(sat)}$ | Collector-emitter saturation voltage | $V_{GE} = 15V, I_C = 5A$ | | 2.2 | 2.5 | V |
| | | $V_{GE} = 15V, I_C = 5A, T_C = 125^{\circ}C$ | | 1.8 | | V |
| $V_{GE(th)}$ | Gate threshold voltage | $V_{CE} = V_{GE}, I_C = 250 \mu A$ | 4.5 | | 6.5 | V |
| I_{CES} | Collector cut-off current ($V_{GE} = 0$) | $V_{CE} = \text{Max Rating}, T_C = 25^{\circ}C$ | | | 150 | μA |
| | | $V_{CE} = \text{Max Rating}, T_C = 125^{\circ}C$ | | | 1 | mA |
| I_{GES} | Gate-emitter leakage current ($V_{CE} = 0$) | $V_{GE} = \pm 20V, V_{CE} = 0$ | | | ± 100 | nA |
| g_{fs} | Forward transconductance | $V_{CE} = 15V, I_C = 5A$ | | 15 | | S |

Table 4. Dynamic

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|-------------------------------------|------------------------------|---|------|------|------|------|
| C_{ies} C_{oes} C_{res} | Input capacitance | $V_{CE} = 25V, f = 1MHz,$ $V_{GE} = 0$ | | 380 | | pF |
| | Output capacitance | | | 46 | | pF |
| | Reverse transfer capacitance | | | 8.5 | | pF |
| Q_g Q_{ge} Q_{gc} | Total gate charge | $V_{CE} = 390V, I_C = 5A,$ | | 19 | | nC |
| | Gate-emitter charge | $V_{GE} = 15V,$ | | 5 | | nC |
| | Gate-collector charge | (see Figure 16) | | 9 | | nC |

Table 5. Switching on/off (inductive load)

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|----------------|-----------------------|--|------|------|------|------------|
| $t_{d(on)}$ | Turn-on delay time | $V_{CC} = 390V, I_C = 5A$ | | 17 | | ns |
| t_r | Current rise time | $R_G = 10\Omega, V_{GE} = 15V, T_J = 25^\circ C$ | | 6 | | ns |
| $(di/dt)_{on}$ | Turn-on current slope | (see Figure 17) | | 655 | | A/ μs |
| $t_{d(on)}$ | Turn-on delay time | $V_{CC} = 390V, I_C = 5A$ | | 16.5 | | ns |
| t_r | Current rise time | $R_G = 10\Omega, V_{GE} = 15V, T_J = 125^\circ C$ | | 6.5 | | ns |
| $(di/dt)_{on}$ | Turn-on current slope | (see Figure 17) | | 575 | | A/ μs |
| $t_r(V_{off})$ | Off voltage rise time | $V_{CC} = 390V, I_C = 5A,$ | | 33 | | ns |
| $t_{d(off)}$ | Turn-off delay time | $R_{GE} = 10\Omega, V_{GE} = 15V, T_J = 25^\circ C$ | | 72 | | ns |
| t_f | Current fall time | (see Figure 17) | | 82 | | ns |
| $t_r(V_{off})$ | Off voltage rise time | $V_{CC} = 390V, I_C = 5A,$ | | 60 | | ns |
| $t_{d(off)}$ | Turn-off delay time | $R_{GE} = 10\Omega, V_{GE} = 15V, T_J = 125^\circ C$ | | 106 | | ns |
| t_f | Current fall time | (see Figure 17) | | 136 | | ns |

Table 6. Switching energy (inductive load)

| Symbol | Parameter | Test conditions | Min | Typ | Max | Unit |
|-----------------|---------------------------|--|-----|-----|-----|---------|
| $E_{on}^{(1)}$ | Turn-on switching losses | $V_{CC} = 390V, I_C = 5A$ | | 55 | | μJ |
| $E_{off}^{(2)}$ | Turn-off switching losses | $R_G = 10\Omega, V_{GE} = 15V, T_J = 25^\circ C$ | | 85 | | μJ |
| E_{ts} | Total switching losses | (see Figure 17) | | 140 | | μJ |
| $E_{on}^{(1)}$ | Turn-on switching losses | $V_{CC} = 390V, I_C = 5A$ | | 87 | | μJ |
| $E_{off}^{(2)}$ | Turn-off switching losses | $R_G = 10\Omega, V_{GE} = 15V,$ | | 162 | | μJ |
| E_{ts} | Total switching losses | $T_J = 125^\circ C$ (see Figure 17) | | 249 | | μJ |

1. E_{on} is the turn-on losses when a typical diode is used in the test circuit in figure 2. If the IGBT is offered in a package with a co-pak diode, the co-pak diode is used as external diode. IGBTs & Diode are at the same temperature (25°C and 125°C)
2. Turn-off losses include also the tail of the collector current

2.1 Electrical characteristics (curves)

Figure 1. Output characteristics

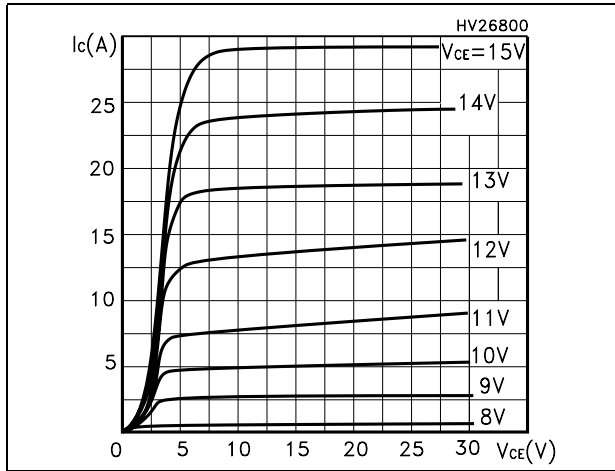


Figure 2. Transfer characteristics

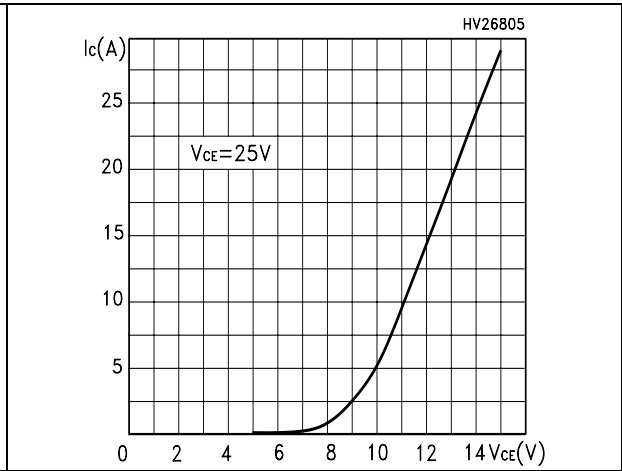


Figure 3. Transconductance

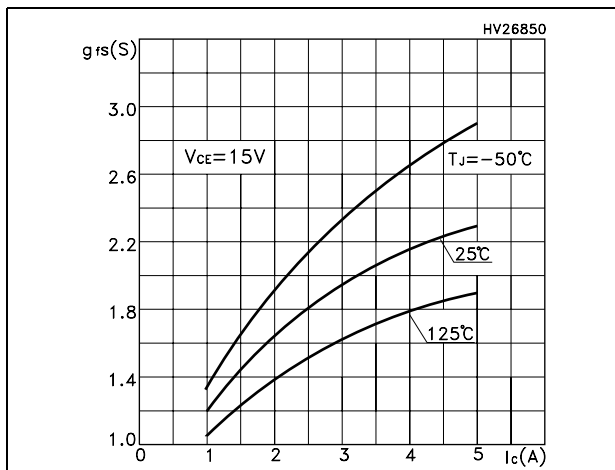


Figure 4. Collector-emitter on voltage vs temperature

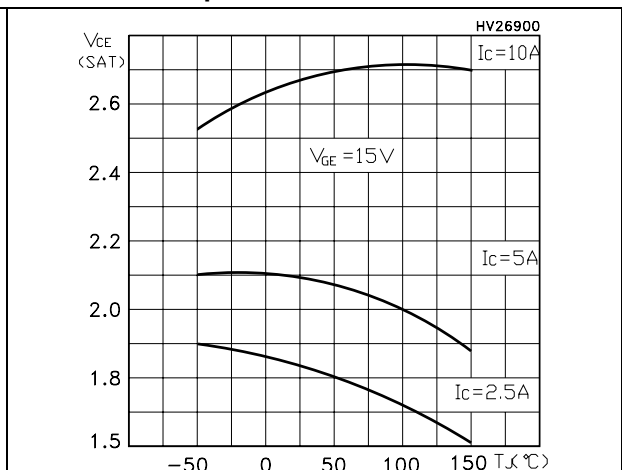


Figure 5. Gate charge vs gate-source voltage

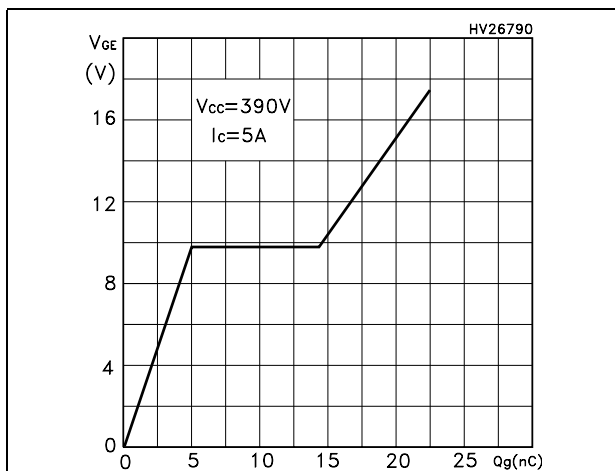


Figure 6. Capacitance variations

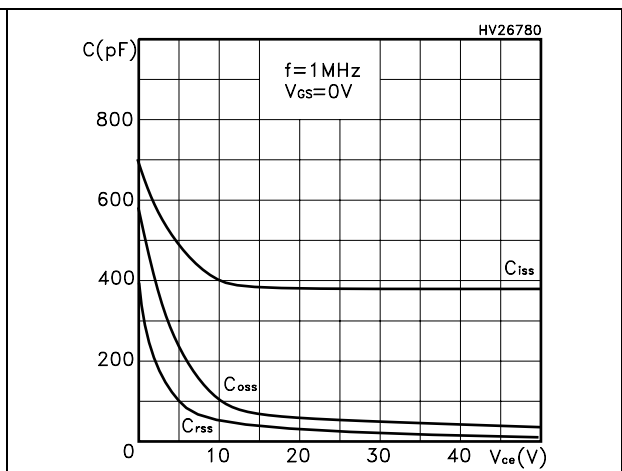


Figure 7. Normalized gate threshold voltage vs temperature

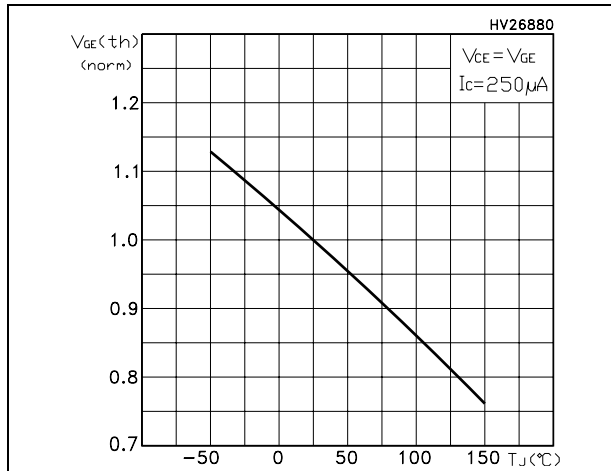


Figure 8. Collector-emitter on voltage vs collector current

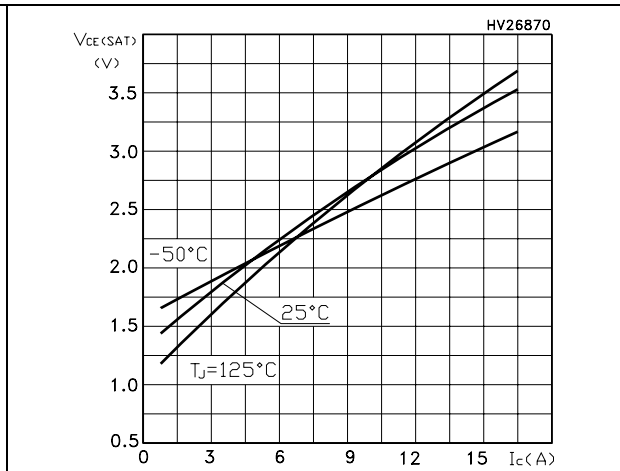


Figure 9. Normalized breakdown voltage vs temperature

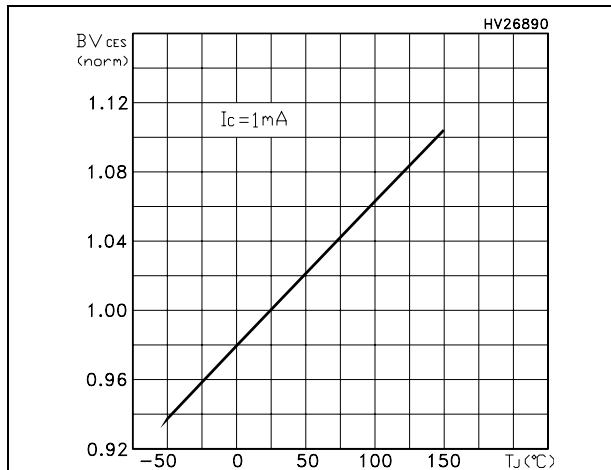


Figure 10. Switching losses vs temperature

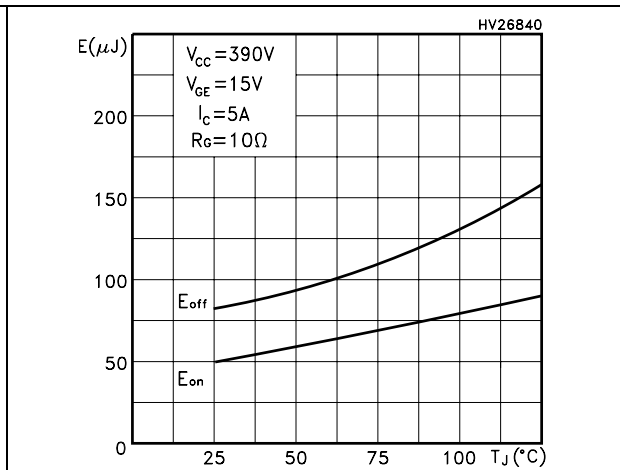


Figure 11. Switching losses vs gate resistance

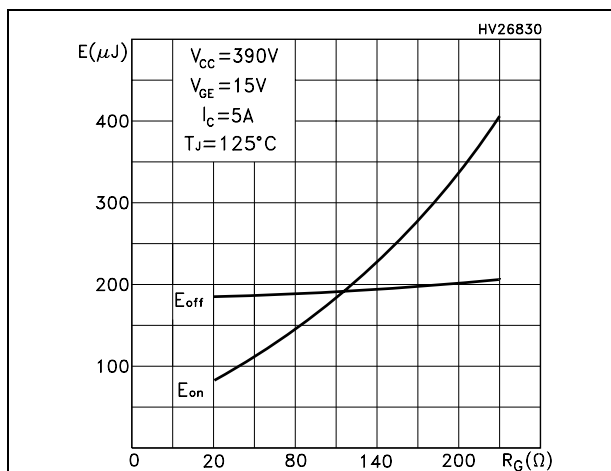


Figure 12. Switching losses vs collector current

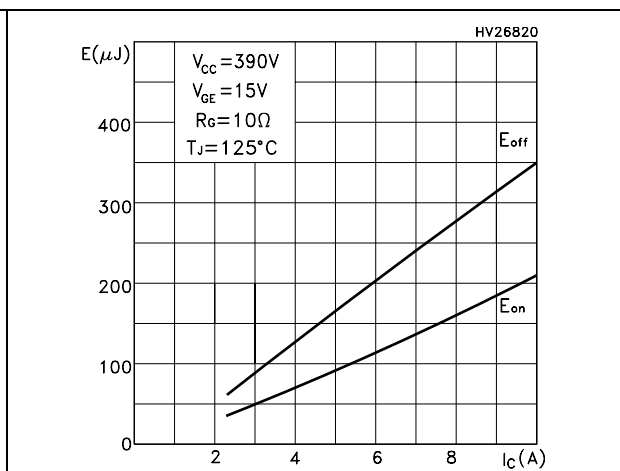


Figure 13. Thermal impedance

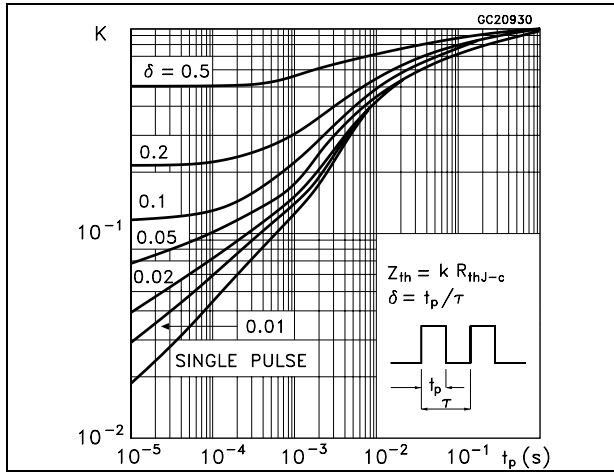
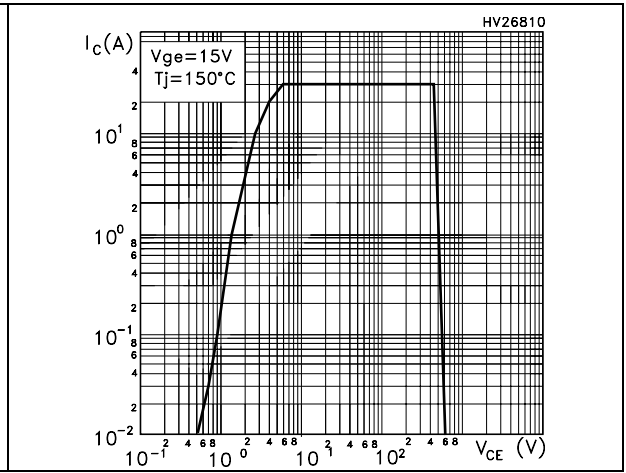


Figure 14. Turn-off SOA



3 Test circuit

Figure 15. Test circuit for inductive load switching

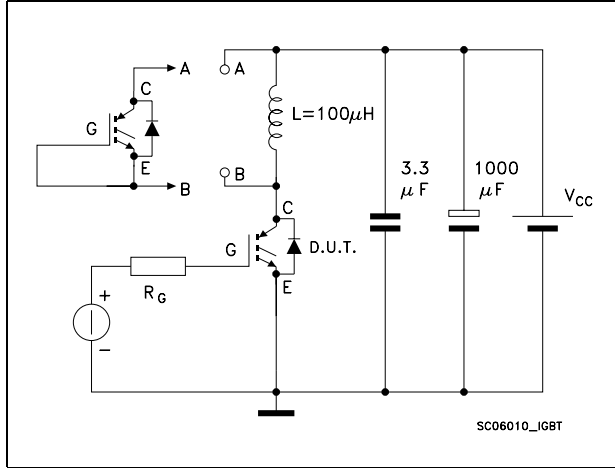


Figure 16. Gate charge test circuit

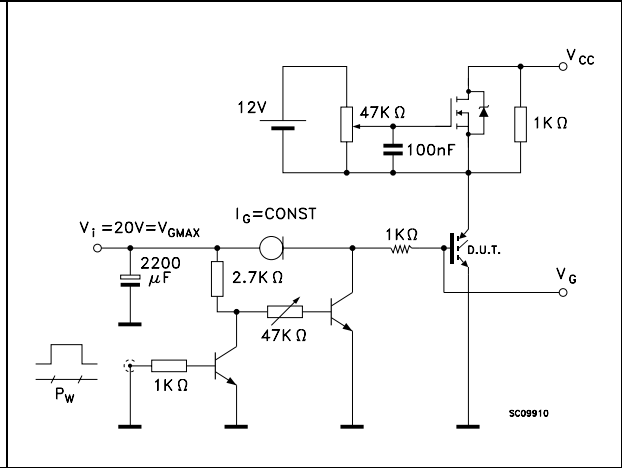


Figure 17. Switching waveform

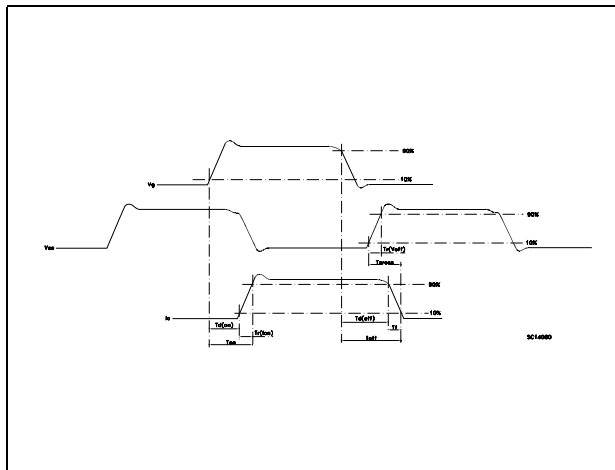
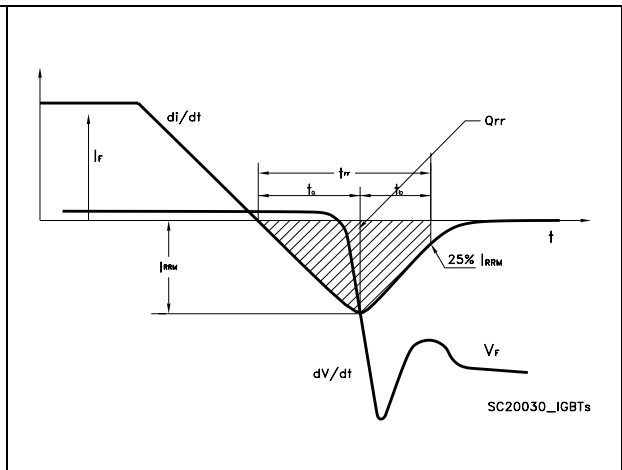


Figure 18. Diode recovery time waveform

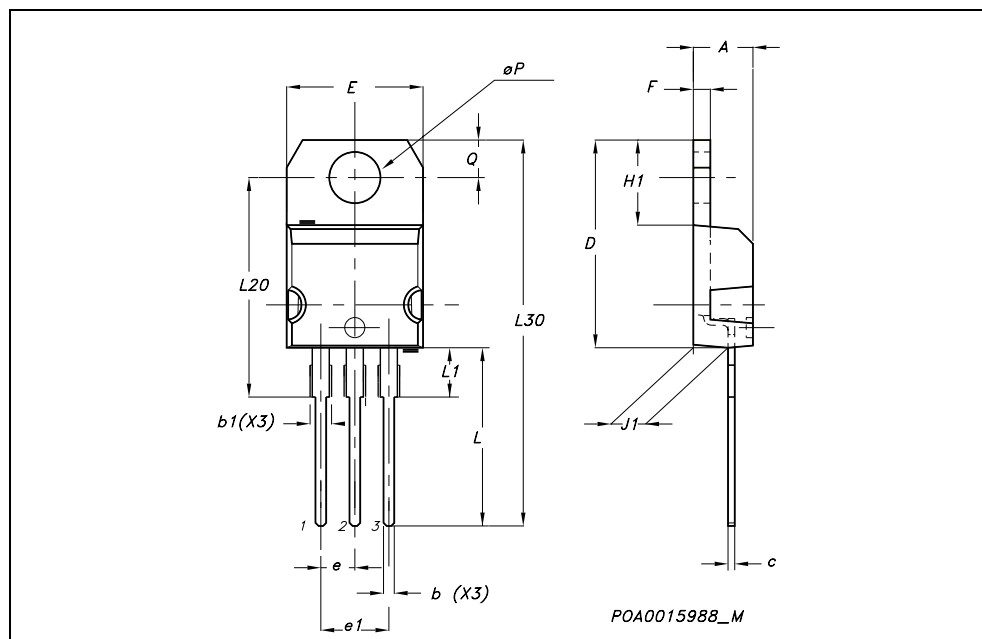


4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com

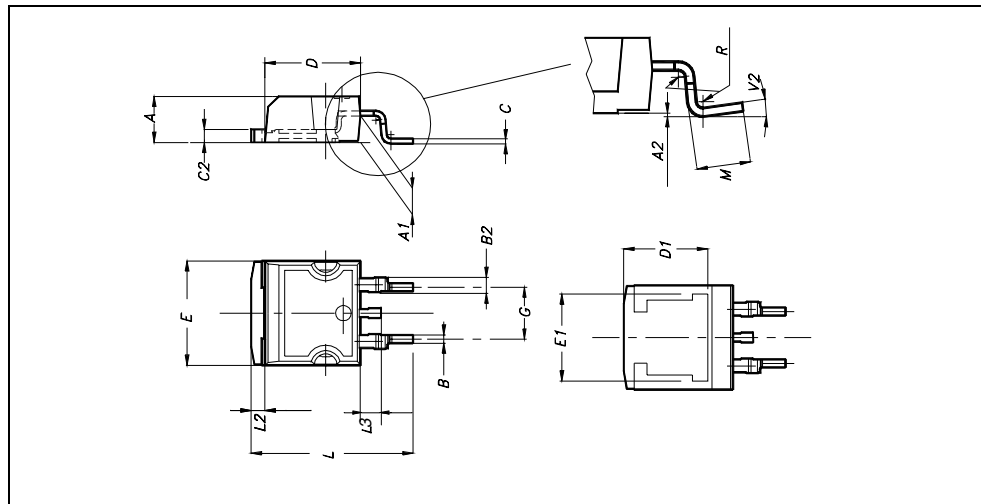
TO-220 MECHANICAL DATA

| DIM. | mm. | | | inch | | |
|------|-------|-------|-------|-------|-------|-------|
| | MIN. | TYP. | MAX. | MIN. | TYP. | MAX. |
| A | 4.40 | | 4.60 | 0.173 | | 0.181 |
| b | 0.61 | | 0.88 | 0.024 | | 0.034 |
| b1 | 1.15 | | 1.70 | 0.045 | | 0.066 |
| c | 0.49 | | 0.70 | 0.019 | | 0.027 |
| D | 15.25 | | 15.75 | 0.60 | | 0.620 |
| E | 10 | | 10.40 | 0.393 | | 0.409 |
| e | 2.40 | | 2.70 | 0.094 | | 0.106 |
| e1 | 4.95 | | 5.15 | 0.194 | | 0.202 |
| F | 1.23 | | 1.32 | 0.048 | | 0.052 |
| H1 | 6.20 | | 6.60 | 0.244 | | 0.256 |
| J1 | 2.40 | | 2.72 | 0.094 | | 0.107 |
| L | 13 | | 14 | 0.511 | | 0.551 |
| L1 | 3.50 | | 3.93 | 0.137 | | 0.154 |
| L20 | | 16.40 | | | 0.645 | |
| L30 | | 28.90 | | | 1.137 | |
| øP | 3.75 | | 3.85 | 0.147 | | 0.151 |
| Q | 2.65 | | 2.95 | 0.104 | | 0.116 |



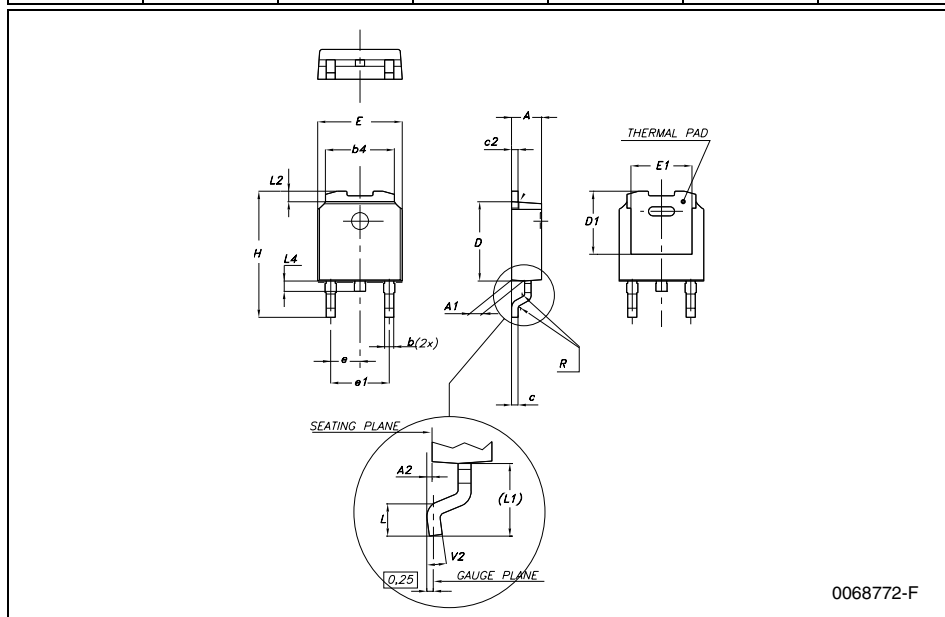
D²PAK MECHANICAL DATA

| DIM. | mm. | | | inch | | |
|------|------|-----|-------|-------|-------|-------|
| | MIN. | TYP | MAX. | MIN. | TYP. | MAX. |
| A | 4.4 | | 4.6 | 0.173 | | 0.181 |
| A1 | 2.49 | | 2.69 | 0.098 | | 0.106 |
| A2 | 0.03 | | 0.23 | 0.001 | | 0.009 |
| B | 0.7 | | 0.93 | 0.027 | | 0.036 |
| B2 | 1.14 | | 1.7 | 0.044 | | 0.067 |
| C | 0.45 | | 0.6 | 0.017 | | 0.023 |
| C2 | 1.23 | | 1.36 | 0.048 | | 0.053 |
| D | 8.95 | | 9.35 | 0.352 | | 0.368 |
| D1 | | 8 | | | 0.315 | |
| E | 10 | | 10.4 | 0.393 | | |
| E1 | | 8.5 | | | 0.334 | |
| G | 4.88 | | 5.28 | 0.192 | | 0.208 |
| L | 15 | | 15.85 | 0.590 | | 0.625 |
| L2 | 1.27 | | 1.4 | 0.050 | | 0.055 |
| L3 | 1.4 | | 1.75 | 0.055 | | 0.068 |
| M | 2.4 | | 3.2 | 0.094 | | 0.126 |
| R | | 0.4 | | | 0.015 | |
| V2 | 0° | | 4° | | | |



DPAK MECHANICAL DATA

| DIM. | mm. | | | inch | | |
|------|------|------|------|-------|-------|-------|
| | MIN. | TYP. | MAX. | MIN. | TYP. | MAX. |
| A | 2.2 | | 2.4 | 0.086 | | 0.094 |
| A1 | 0.9 | | 1.1 | 0.035 | | 0.043 |
| A2 | 0.03 | | 0.23 | 0.001 | | 0.009 |
| B | 0.64 | | 0.9 | 0.025 | | 0.035 |
| b4 | 5.2 | | 5.4 | 0.204 | | 0.212 |
| C | 0.45 | | 0.6 | 0.017 | | 0.023 |
| C2 | 0.48 | | 0.6 | 0.019 | | 0.023 |
| D | 6 | | 6.2 | 0.236 | | 0.244 |
| D1 | | 5.1 | | | 0.200 | |
| E | 6.4 | | 6.6 | 0.252 | | 0.260 |
| E1 | | 4.7 | | | 0.185 | |
| e | | 2.28 | | | 0.090 | |
| e1 | 4.4 | | 4.6 | 0.173 | | 0.181 |
| H | 9.35 | | 10.1 | 0.368 | | 0.397 |
| L | 1 | | | 0.039 | | |
| (L1) | | 2.8 | | | 0.110 | |
| L2 | | 0.8 | | | 0.031 | |
| L4 | 0.6 | | 1 | 0.023 | | 0.039 |
| R | | 0.2 | | | 0.008 | |
| V2 | 0° | | 8° | 0° | | 8° |



0068772-F

5 Packaging mechanical data

D²PAK FOOTPRINT



TAPE AND REEL SHIPMENT

TAPE MECHANICAL DATA

| DIM. | mm | | inch | |
|------|------|------|--------|--------|
| | MIN. | MAX. | MIN. | MAX. |
| A0 | 10.5 | 10.7 | 0.413 | 0.421 |
| B0 | 15.7 | 15.9 | 0.618 | 0.626 |
| D | 1.5 | 1.6 | 0.059 | 0.063 |
| D1 | 1.59 | 1.61 | 0.062 | 0.063 |
| E | 1.65 | 1.85 | 0.065 | 0.073 |
| F | 11.4 | 11.6 | 0.449 | 0.456 |
| K0 | 4.8 | 5.0 | 0.189 | 0.197 |
| P0 | 3.9 | 4.1 | 0.153 | 0.161 |
| P1 | 11.9 | 12.1 | 0.468 | 0.476 |
| P2 | 1.9 | 2.1 | 0.075 | 0.082 |
| R | 50 | | 1.574 | |
| T | 0.25 | 0.35 | 0.0098 | 0.0137 |
| W | 23.7 | 24.3 | 0.933 | 0.956 |

REEL MECHANICAL DATA

| DIM. | mm | | inch | |
|------|------|------|-------|--------|
| | MIN. | MAX. | MIN. | MAX. |
| A | | 330 | | 12.992 |
| B | 1.5 | | 0.059 | |
| C | 12.8 | 13.2 | 0.504 | 0.520 |
| D | 20.2 | | 0.795 | |
| G | 24.4 | 26.4 | 0.960 | 1.039 |
| N | 100 | | 3.937 | |
| T | | 30.4 | | 1.197 |

| BASE QTY | BULK QTY |
|----------|----------|
| 1000 | 1000 |

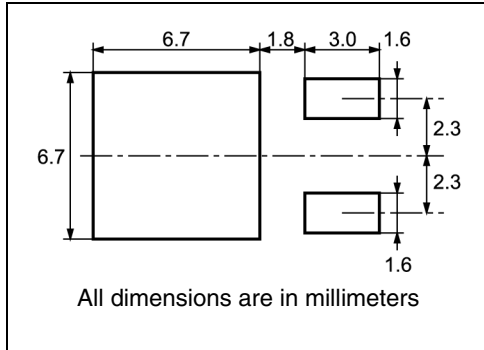
10 pitches cumulative tolerance on tape +/- 0.2 mm

FEED DIRECTION

Bending radius R min.

* on sales type

DPAK FOOTPRINT



TAPE AND REEL SHIPMENT

| DIM. | mm | | inch | |
|------|------|------|-------|--------|
| | MIN. | MAX. | MIN. | MAX. |
| A | | 330 | | 12.992 |
| B | 1.5 | | 0.059 | |
| C | 12.8 | 13.2 | 0.504 | 0.520 |
| D | 20.2 | | 0.795 | |
| G | 16.4 | 18.4 | 0.645 | 0.724 |
| N | 50 | | 1.968 | |
| T | | 22.4 | | 0.881 |

| BASE QTY | | BULK QTY | |
|----------|--|----------|--|
| 2500 | | 2500 | |

| DIM. | mm | | inch | |
|------|------|------|-------|-------|
| | MIN. | MAX. | MIN. | MAX. |
| A0 | 6.8 | 7 | 0.267 | 0.275 |
| B0 | 10.4 | 10.6 | 0.409 | 0.417 |
| B1 | | 12.1 | | 0.476 |
| D | 1.5 | 1.6 | 0.059 | 0.063 |
| D1 | 1.5 | | 0.059 | |
| E | 1.65 | 1.85 | 0.065 | 0.073 |
| F | 7.4 | 7.6 | 0.291 | 0.299 |
| K0 | 2.55 | 2.75 | 0.100 | 0.108 |
| P0 | 3.9 | 4.1 | 0.153 | 0.161 |
| P1 | 7.9 | 8.1 | 0.311 | 0.319 |
| P2 | 1.9 | 2.1 | 0.075 | 0.082 |
| R | 40 | | 1.574 | |
| W | 15.7 | 16.3 | 0.618 | 0.641 |

6 Revision history

Table 7. Revision history

| Date | Revision | Changes |
|-------------|----------|--|
| 21-Nov-2005 | 1 | New release |
| 06-Dic-2005 | 2 | Inserted row on Table 1.: Absolute maximum ratings |
| 06-Mar-2006 | 3 | The document has been reformatted |
| 06-Jun-2006 | 4 | Inserted DPAK |
| 08-Feb-2007 | 5 | Description has been updated |

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